Surface Mount Schottky Power Rectifier

SMB Power Surface Mount Package

MBRS240LT3G, NRVBS240LT3G, NRVBS240LN

These devices employ the Schottky Barrier principle in a metal−to−silicon power rectifier. Features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency switching power supplies; free wheeling diodes and polarity protection diodes.

Features

- Compact Package with J−Bend Leads Ideal for Automated Handling
- Highly Stable Oxide Passivated Junction
- Guard−Ring for Overvoltage Protection
- Low Forward Voltage Drop
- ESD Ratings:
  - Human Body Model = 3B (> 16000 V)
  - Machine Model = C (> 400 V)
- NRVB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q101 Qualified and PPAP Capable*
- These are Pb−Free Devices

Mechanical Characteristics

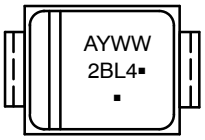
- Case: Molded Epoxy
- Epoxy Meets UL 94 V−0 @ 0.125 in
- Weight: 95 mg (Approximately)
- Cathode Polarity Band
- Maximum Temperature of 260°C/10 Seconds for Soldering
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable

SCHOTTKY BARRIER RECTIFIER 2.0 AMPERES, 40 VOLTS



SMB
CASE 403A

MARKING DIAGRAM



2BL4	= Specific Device Code
A	= Assembly Location**
Y	= Year
WW	= Work Week
▪	= Pb−Free Package

(Note: Microdot may be in either location)

**The Assembly Location code (A) is front side optional. In cases where the Assembly Location is stamped in the package bottom (molding ejecter pin), the front side assembly code may be blank.

ORDERING INFORMATION

Device	Package	Shipping†
MBRS240LT3G	SMB (Pb−Free)	2,500 / Tape & Reel
NRVBS240LT3G*	SMB (Pb−Free)	2,500 / Tape & Reel
NRVBS240LNT3G*	SMB (Pb−Free)	2,500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	40	V
Average Rectified Forward Current (At Rated V_R, T_C = 100°C)	I_O	2.0	A
Peak Repetitive Forward Current (At Rated V_R, Square Wave, 20 kHz, T_C = 105°C)	I_{FRM}	4.0	A
Non−Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I_{FSM}	25	A
Storage Temperature	T_{stg}, T_C	−55 to +150	°C
Operating Junction Temperature	T_J	−55 to +150	°C
Voltage Rate of Change (Rated V_R, T_J = 25°C)	dv/dt	10,000	V/μs

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction−to−Lead (Note 1) Thermal Resistance, Junction−to−Ambient (Note 2)	$R_{\theta JL}$ $R_{\theta JA}$	18 78	°C/W

1. Mounted with minimum recommended pad size, PC Board FR4.
2. 1 inch square pad size (1 x 0.5 inch for each lead) on FR4 board.

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Value		Unit
Maximum Instantaneous Forward Voltage (Note 3) see Figure 2	V_F	**T_J = 25°C**	**T_J = 125°C**	V
(I_F = 2.0 A) (I_F = 4.0 A)		0.43 0.54	0.375 0.55	
Maximum Instantaneous Reverse Current (Note 3) see Figure 4	I_R	**T_J = 25°C**	**T_J = 100°C**	mA
(V_R = 40 V) (V_R = 20 V)		2.0 0.5	60 40	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: Pulse Width ≤ 250 μs, Duty Cycle ≤ 2.0%.

TYPICAL CHARACTERISTICS

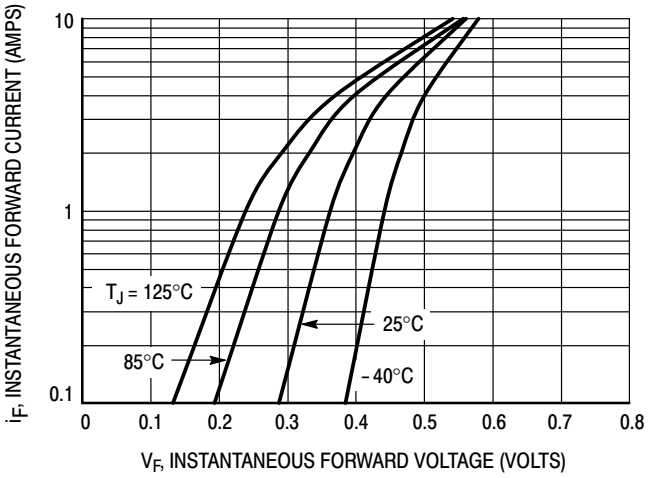


Figure 1. Typical Forward Voltage

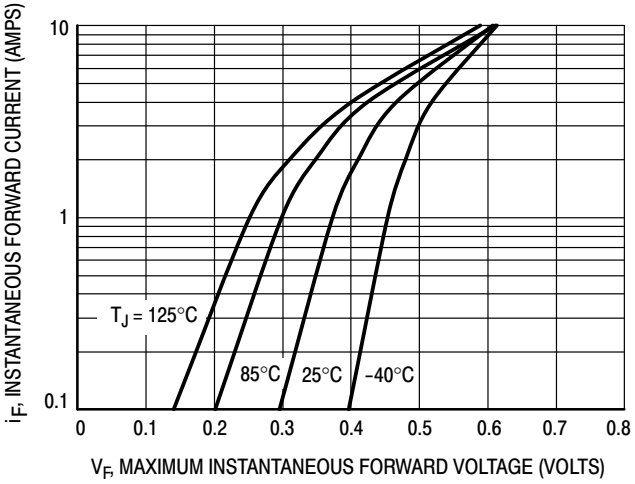


Figure 2. Maximum Forward Voltage

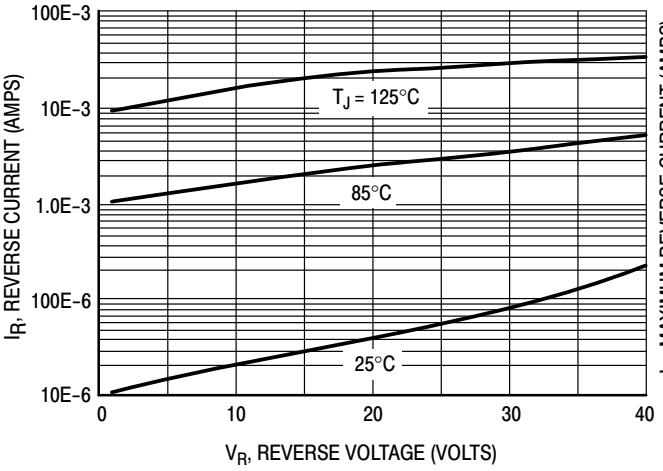


Figure 3. Typical Reverse Current

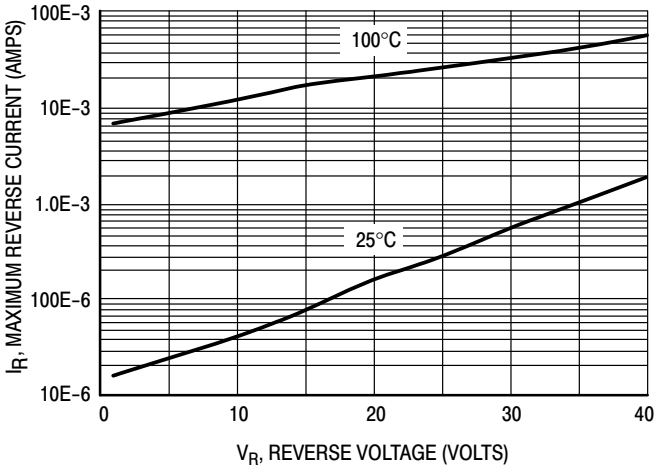


Figure 4. Maximum Reverse Current

TYPICAL CHARACTERISTICS

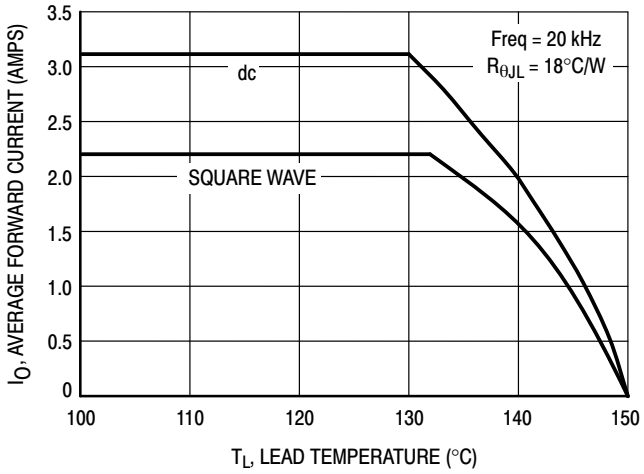


Figure 5. Current Derating

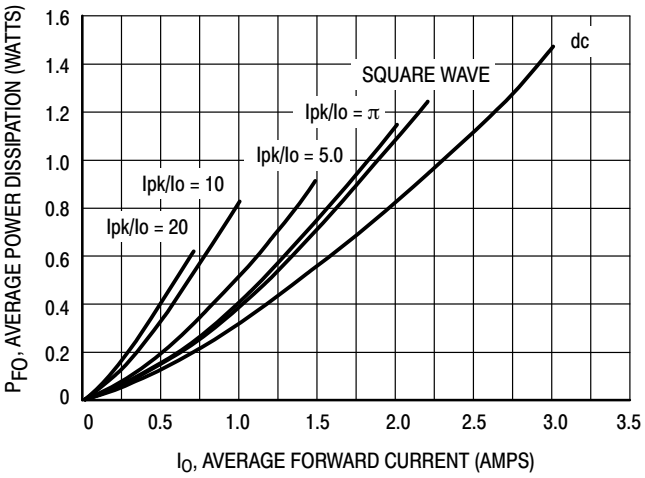


Figure 6. Forward Power Dissipation

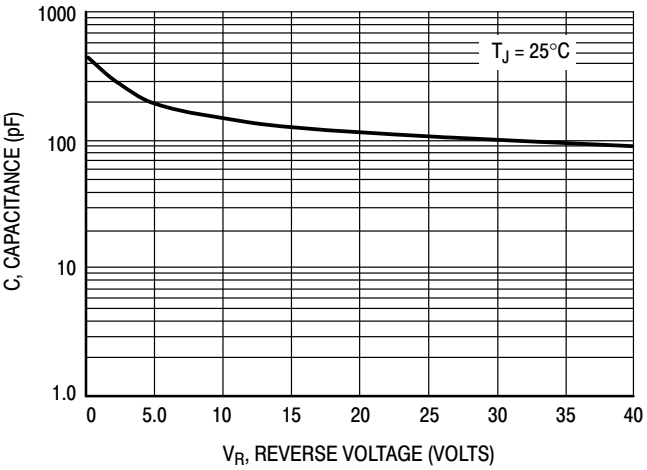


Figure 7. Capacitance

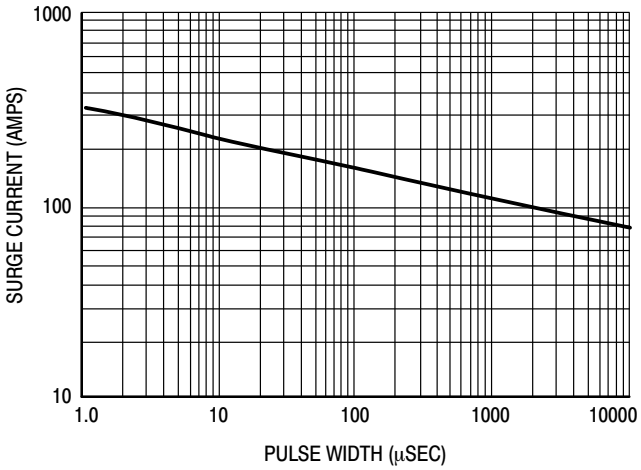


Figure 8. Maximum Non−Repetitive Forward Surge Current

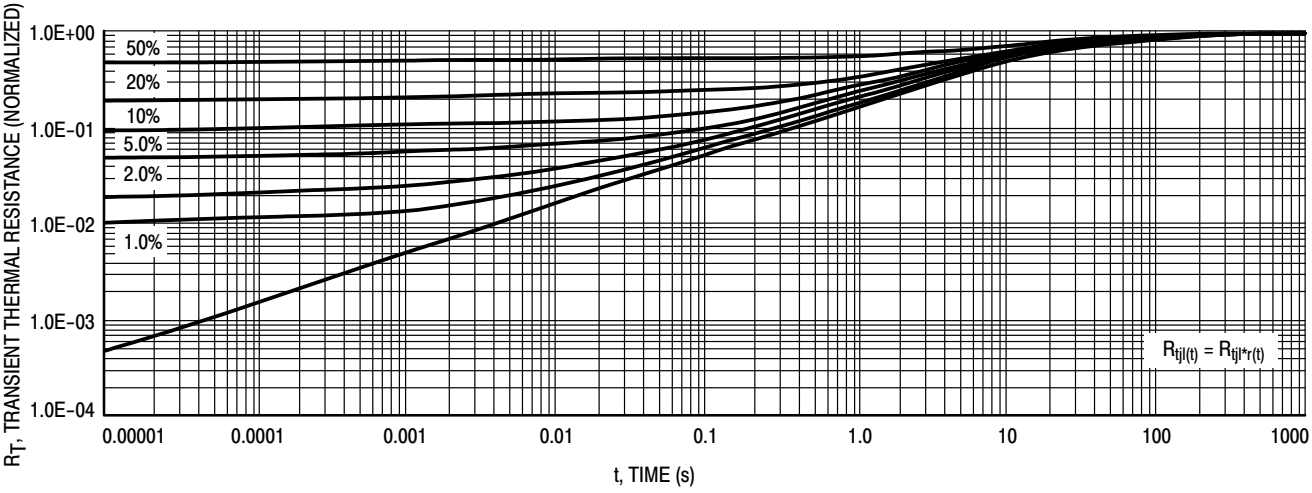


Figure 9. Thermal Response

SMB
CASE 403A−03
ISSUE J

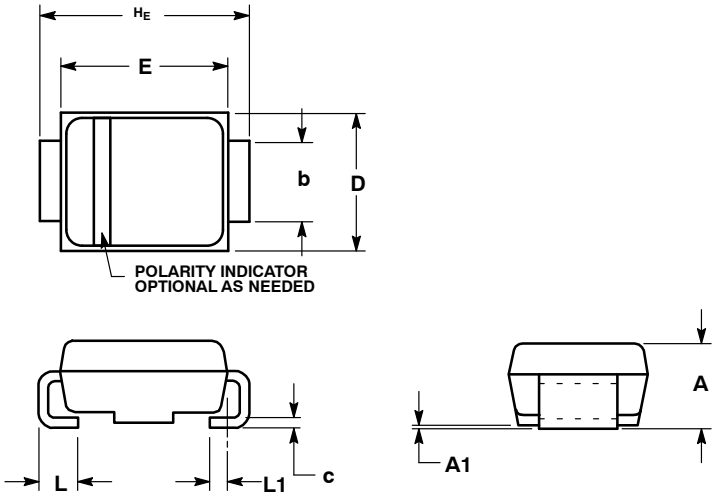
DATE 19 JUL 2012



SCALE 1:1
Polarity Band



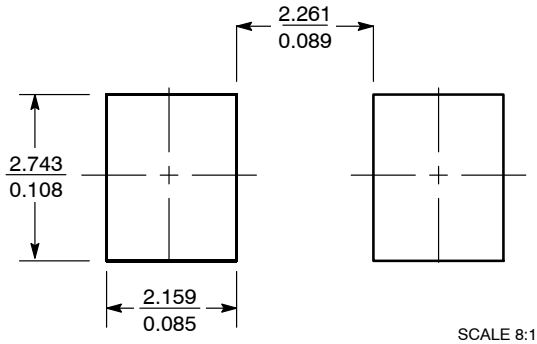
SCALE 1:1
Non−Polarity Band



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION b SHALL BE MEASURED WITHIN DIMENSION L1.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
A	1.95	2.30	2.47	0.077	0.091	0.097
A1	0.05	0.10	0.20	0.002	0.004	0.008
b	1.96	2.03	2.20	0.077	0.080	0.087
c	0.15	0.23	0.31	0.006	0.009	0.012
D	3.30	3.56	3.95	0.130	0.140	0.156
E	4.06	4.32	4.60	0.160	0.170	0.181
H_E	5.21	5.44	5.60	0.205	0.214	0.220
L	0.76	1.02	1.60	0.030	0.040	0.063
L1	0.51 REF			0.020 REF		

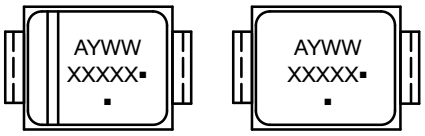
SOLDERING FOOTPRINT*



SCALE 8:1 (mm / inches)

*For additional information on our Pb−Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



Polarity Band **Non−Polarity Band**

XXXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

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